

ABSTRACT OF THE DISCLOSURE

EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

The object of the present invention is to provide an epoxy resin compositions for encapsulating of semiconductors containing no bromine compounds and no antimony oxide and excellent in flame retardancy, moisture resistance, moldability, curability and electric characteristics. This composition is an epoxy resin composition containing (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator, (D) an inorganic filler and (E) a red phosphorus-based flame retardant, wherein the improvement comprises the red phosphorus-based flame retardant (E) having a total content of phosphate ion and phosphite ion extracted from the retardant when subjected to extraction with water at 80°C for 20 hours is not more than 2000 ppm, the amount of the red phosphorus in the red phosphorus-based retardant being 20-40% by weight and the red phosphorus-based retardant being contained in an amount of 0.5-5% by weight in the whole resin composition.



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